

The documentation and process conversion measures necessary to comply with this revision shall be completed by 20 November 2001.

INCH POUND

MIL-PRF-19500/673
AMENDMENT 1
20 August 2001

PERFORMANCE SPECIFICATION

SEMICONDUCTOR DEVICE, FIELD EFFECT RADIATION HARDENED (TOTAL DOSE AND SINGLE EVENT EFFECTS) TRANSISTOR, N-CHANNEL, SILICON TYPES 2N7468U2 AND 2N7469U2 JANTXVR, F, G, AND H, AND JANSR, F, G, AND H

This amendment forms a part of MIL-PRF-19500/673, dated 9 March 2001 and is approved for use by all Departments and Agencies of the Department of Defense.

PAGE 8

4.5.2, second sentence, delete " $R_{\theta JC} = 0.42^{\circ}\text{C/W}$ " substitute " $R_{\theta JC} = 0.50^{\circ}\text{C/W}$ ".

4.5.2b, delete "13.33 A" and substitute "13.88 A".

4.5.2d, delete "15 V" and substitute "12 V".

4.5.3b, delete "13.33 A" and substitute "13.88 A".

4.5.3d, delete "15 V" and substitute "12 V".

PAGE 9

TABLE I, subgroup 2, thermal impedance, method 3161, minimum limits, delete "0.37" substitute "0.38" in maximum limit column.

PAGE 12

TABLE I, subgroup 2, V, conditions, delete " $I_D = I_{D1}$ " and substitute with " $I_D = I_{D2}$ ".

PAGE 14

TABLE III, subgroup 7, electrical measurements, LET = 37 MeV-cm²/mg, insitu bias conditions, delete the conditions "VDS = 60V & VGS = -20V and VDS = 100V & VGS = -20V" and substitute "VDS = 60V & VGS = -15V, VDS = 40V & VGS = -20V and VDS = 100V & VGS = -20V".

FIGURE 2, delete and substitute:

“

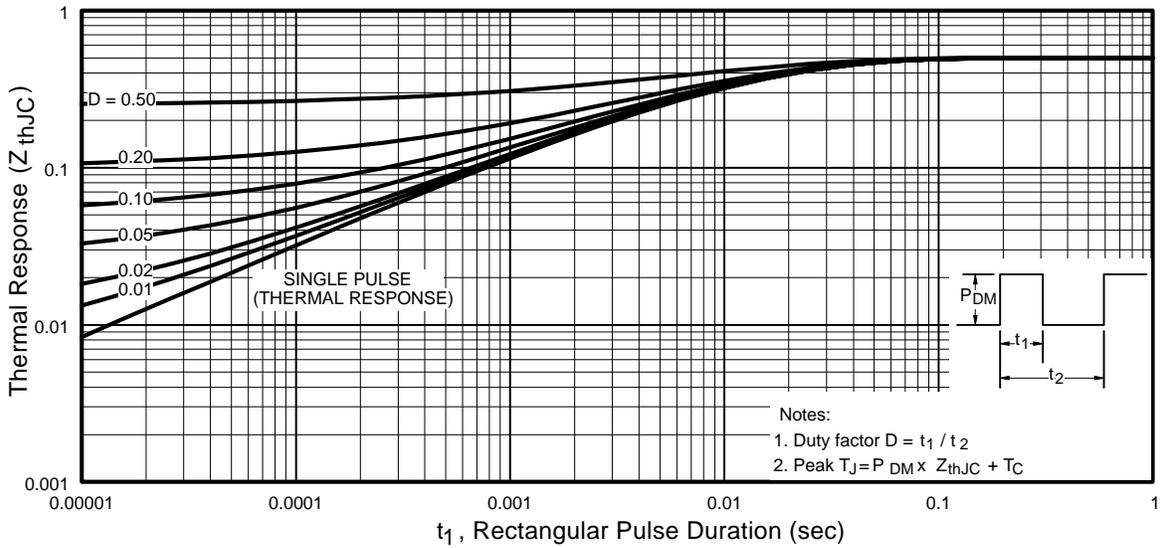


FIGURE 2. Thermal response curve. ”

FIGURE 3, delete and substitute:
“

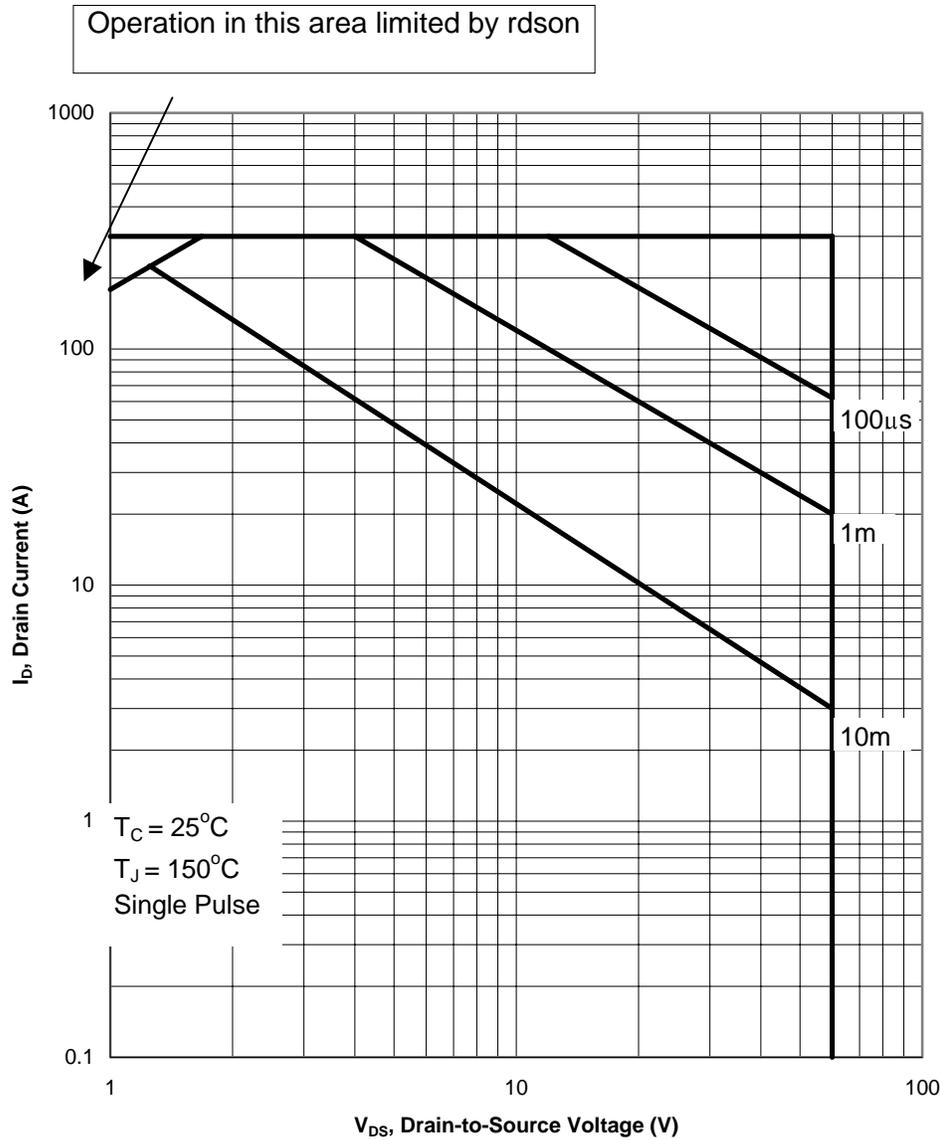


FIGURE 3. Safe operating area graph. "

FIGURE 4, delete and substitute:
"

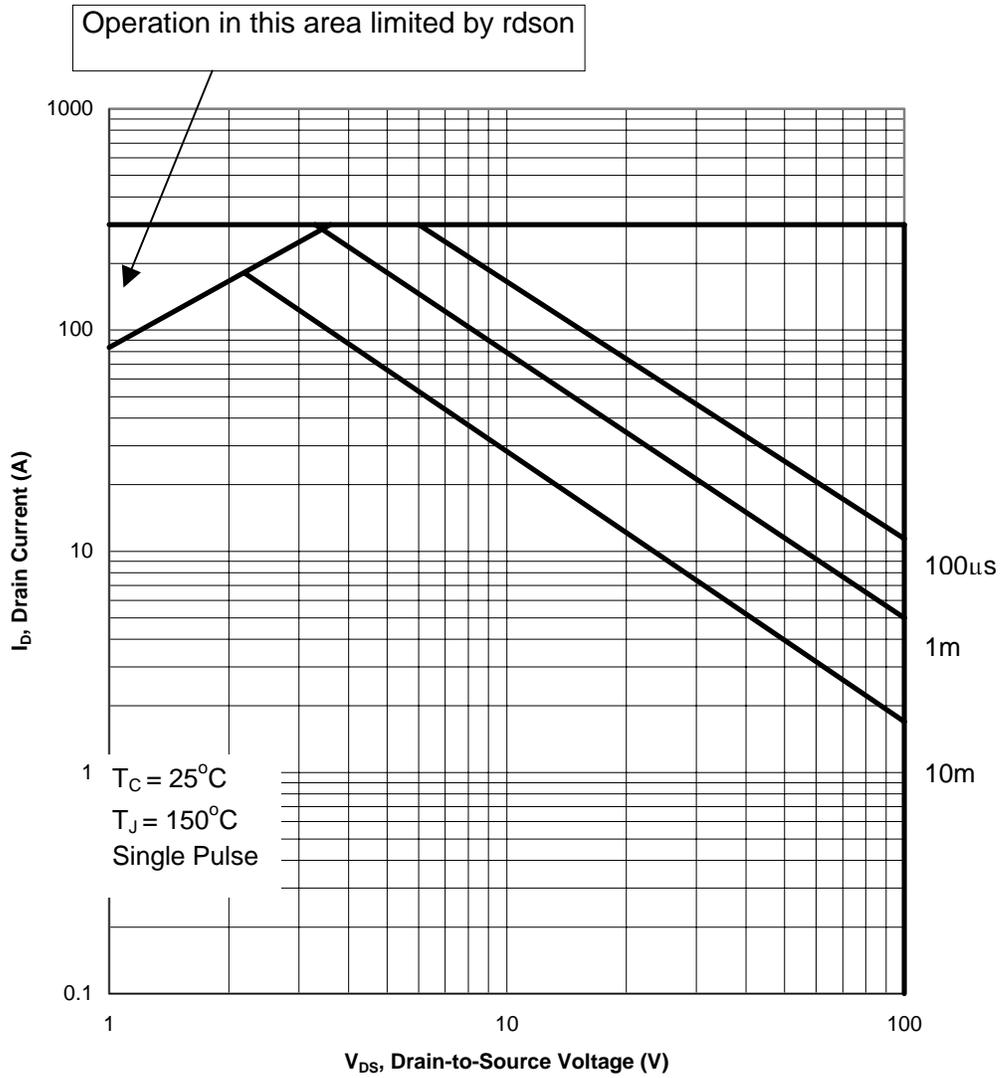


FIGURE 4. Safe operating area graph. "

FIGURE 5, delete and substitute:

“

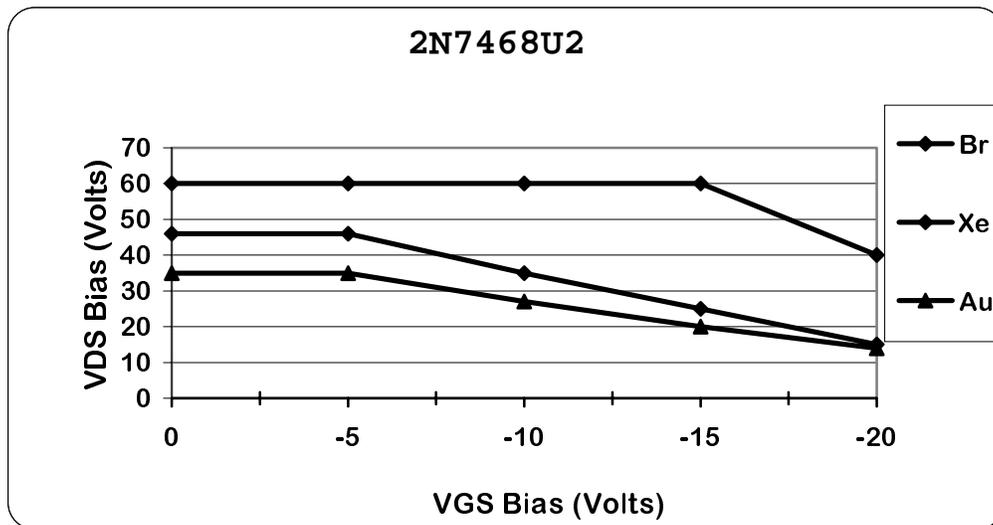


FIGURE 5. SEE safe operating area graph. ”

Custodians:

Army - CR
NAVY - NW
Air Force - 11
NASA - NA
DLA - CC

Preparing activity:
DLA - CC

(Project 5961-2481)

Review Activities:

Army - AV, AR, MI